



KYI-H1200 series (Thermal Gap Filler)

DATA SHEET



-Product picture-

FEATURES:

- Low thermal resistance
- Being recognized as UL94 V-0
- Viscous surface
- Being able to work under low pressure
- Excellent insulation performance and thermal resistance

APPLICATIONS:

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- New energy battery and vehicles industry
- Household appliances
- Wearable equipments

This series of products are environmentally compliant with RoHS 2.0, halogen, and REACH standards.

STORAGE CONDITIONS : Storage in the darkness

STORAGE TEMPERATURE : $\leq 30^{\circ}\text{C}$

STORAGE HUMIDITY : $\leq 70\%$

SHELF LIFE :

Under storage conditions: 2 year

PROPERTIES

Items	Parameter	Unit	Test Method
Color	Gray	-	Visual
Thickness Range	0.5~3	mm	ASTM D 374
Hardness	50	Shore 00	ASTM D 2240
Density	3.5	g/cc	ASTM D 792
Compression Ratio	≥ 15 (@30Psi)	%	ASTM D 575
Rate of oil yield	≤ 1	%	--
UL Certification	V-0	-	UL94
Operating Temperature	-40~125	$^{\circ}\text{C}$	IEC 60068-2-14

THERMAL CHARACTERISTIC

Thermal conductivity	12.0	W/m·K	ASTM D 5470
Thermal resistance	≤ 0.27 (@10psi&2mm)	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown voltage	≥ 5	kV /mm	ASTM D 149
Volume resistivity	$\geq 10^{10}$	$\Omega\cdot\text{cm}$	ASTM D 257
Dielectric constant	≥ 2	@1MHz	ASTM D 150
Dielectric loss	≤ 0.1	@1MHz	ASTM D 150